

SOT1690-2

TFBGA500S, thin fine-pitch ball grid array package; 500 terminals, 0.65 mm pitch, 14 mm x 17 mm x 0.925 mm body

22 October 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA500S
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	28-02-2017
Manufacturer package code	98ASA00965D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	17	-	mm
seated height	-	0.925	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	500	-	



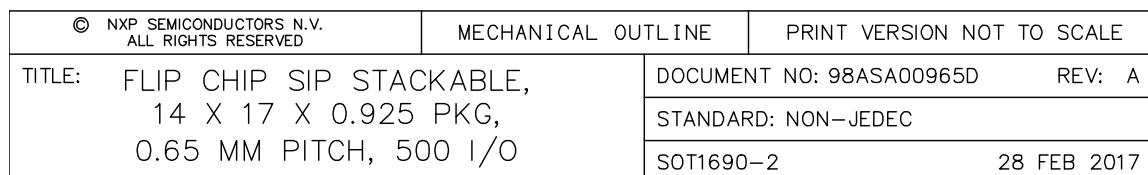


Figure 1. Package outline TFBGA500 (sot1690-2)

TFBGA500S, thin fine-pitch ball grid array package; 500 terminals, 0.65 mm pitch, 14 mm x 17 mm x 0.925 mm body

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
 - 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
 - 4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
 - 6. SCORING OR GROOVES ON TOP SURFACE OF PACKAGE IS NOT PERMITTED.
 - 7. NO VOIDS IN ENCAPSULATION PERMITTED.

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TITLE: FLIP CHIP SIP STACKABLE, 14 X 17 X 0.925 PKG, 0.65 MM PITCH, 500 I/O	DOCUMENT NO: 98ASA00965D REV: A	
	STANDARD: NON–JEDEC	
	SOT1690–2	28 FEB 2017

Figure 2. Package outline note TFBGA500 (sot1690-2)

3 Legal information

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